TSMC-00-143



March 28, 2001

To: Commissioner of Patents and Trademarks

Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572

20 McIntosh Drive

Poughkeepsie, N.Y. 12603

# 475191 MW

Subject:

Serial No. 09/669,159

 $09/25/\overline{001}$ 

H. W. CHEN ET AL

"AN IN-SITU STRIP PROCESS FOR POLYSILICON ETCHING IN DEEP SUB-MICRON TECHNOLOGY"

| Grp. Art Unit: 1763

G. GOUDREAU

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RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated December 28, 2000, please amend the above identified application for patent as follows:

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patent and Trademarks, Washington, D.C. 20231, on March 28, 2001.

Rosemary L. S. Pike, Reg. No. 39,332

Signature

Date March 28, 2001

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